Features

Miniaturized packaging size suitable for high-density applications:
nom 0.039″ x 0.024″ (1.0x0.6mm)

Standard Capacitance 20pF

Low Clamping Voltage:V_C=10V@I_{PP}=8A

Reverse Working (Stand-off) Voltage: 3.3V

Low Leakage current

Response Time is Typically < 1 ns

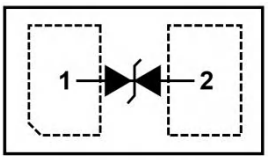
F3

Applications

Smartphones, tablet computers
Blu-ray and DVD recorders and players
Video equipment and accessories



DFN1006-2L(Pb-Free)



Schematic Diagram

Absolute Maximum Rating

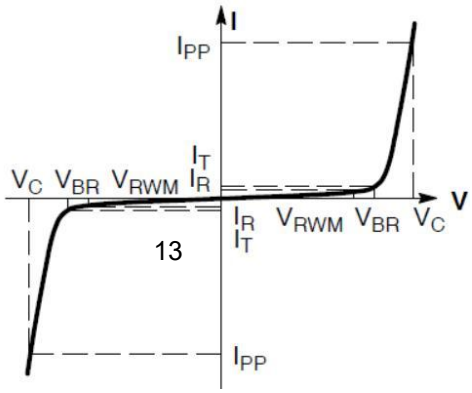
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	P_{PK}	100	W
ESD per IEC 61000−4−2 (Air) ESD per IEC 61000−4−2 (Contact)	V_{ESD}	±30 ±30	kV
Operating Temperature Range	T_J	-55~150	°C
Storage Temperature Range	T_{STG}	-55~150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Stand-off Voltage	VR_{WM}				3.3	V
Reverse Breakdown Voltage	VBR	I_T=1mA	3.5		5	V
Reverse Leakage Current	IR	V_{RWM}=3.3V			500	nA
Clamping Voltage	Vc	I_{PP}=1A,tp=8/20us			6.5	V
		I_{PP}=8A ,tp=8/20us			10	
Junction Capacitance	Cj	V_R=0V, f=1MHz		15	20	pF

Electrical Parameters (TA = 25°C unless otherwise noted)

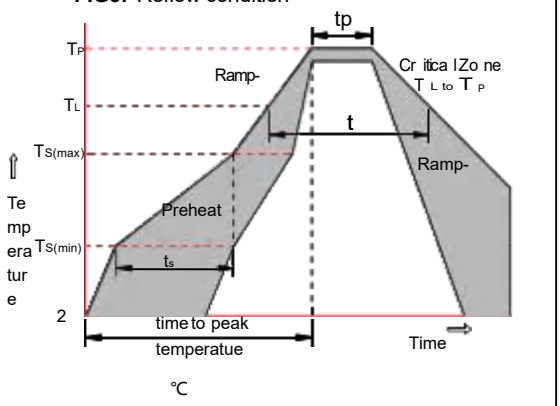
Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T
P_{PK}	Peak Power Dissipation
C	Max. Capacitance @ V_R = 0 and freq.=1 MHz



Soldering parameters

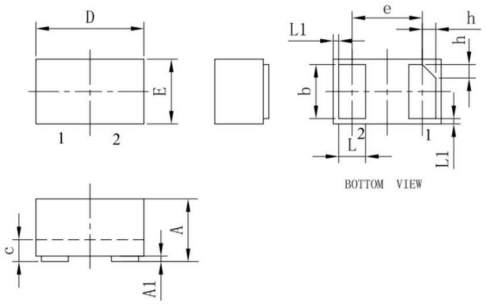
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

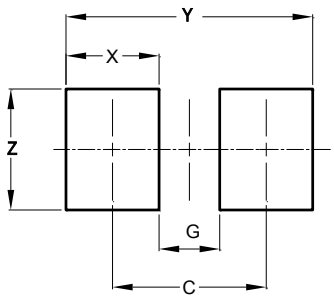
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

DFN1006-2L





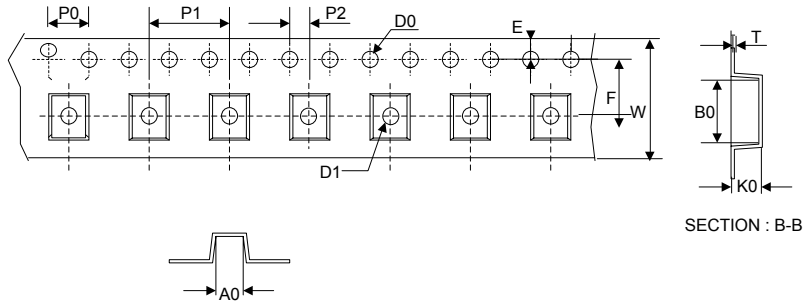
DFN1006-2L

	Millimeters			Inches		
	Min. (mm)	Typ. (mm)	Max. (mm)	Min. (mm)	Typ. (mm)	Max. (mm)
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
c	0.12	0.15	0.18	0.005	0.006	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.59BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.25	0.30	0.35	0.010	0.012	0.013
L1	0.05REF			0.002REF		
h	0.07	0.12	0.17	0.003	0.005	0.007

Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
Y	1.10
Z	0.65

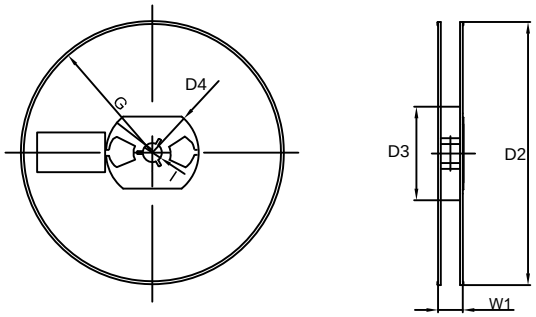
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	2.00±0.20
P2	1.55±0.20
D0	1.55±0.20
D1	0.40±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	1.00±0.20
B0	1.40±0.20
K0	0.75±0.20
T	0.20±0.20

7” Reel



D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0
Quantity: 3000PCS	